

Product Description

The PE4150 is an ultra-high linearity Quad MOSFET mixer with an integrated LO amplifier. The LO amplifier allows for LO drive levels of less than 0dBm to produce IIP3 values similar to a Quad MOSFET Array driven with a 15dBm LO drive. The PE4150 operates with differential signals at the RF and IF ports and the integrated LO buffer amplifier drives the mixer core. It can be used as an upconverter or a downconverter.

The PE4150 is manufactured on Peregrine's UltraCMOS™ process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

Product Specification PE4150

UltraCMOS™ Low Frequency Passive Mixer with Integrated LO Amplifier **Features**

- Ultra-high linearity Quad MOSFET array with integrated LO amplifier
- · Ideal for mobile radio and Up/down conversion applications
- Low conversion loss
- · High LO Isolation
- Packaged in small 20-lead 4x4 mm QFN

Figure 1. Functional Diagram

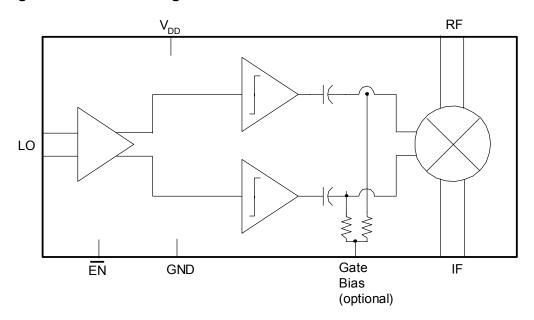


Figure 2. Package Type

4x4 mm 20-Lead QFN





Table 1. AC and DC Electrical Specifications ($V_{DD} = 2.9 \text{ to } 3.1 \text{ V}$, Temperature = -40 to +85 °C unless specified otherwise)

Parameters	Min	Тур	Max	Units
Current Drain (a function of frequency)		8	12	mA
Off state leakage current			20	uA
RF Input Frequency VHF Band UHF1 Band UHF2 Band 700 MHz 800 MHz 900 MHz	136 380 450 764 851 935		174 470 520 776 870 941	MHz MHz MHz MHz MHz MHz
LO Frequency VHF Band UHF1 Band UHF2 Band 700 MHz 800 MHz 900 MHz	245.65 270.35 340.35 873.65 741.35 825.35		283.65 360.35 410.35 885.65 760.35 831.35	MHz MHz MHz MHz MHz MHz
IF Output Frequency	44.85		109.65	MHz
LO Input Power	-10		-6	dBm
RF Input Power			2	dBm
Conversion Loss VHF, UHF1, UHF2 700, 800, and 900 MHz		6.5 7.5	8 8.7	dB dB
3 rd Order Input Intercept (IIP3)	20	25		dBm
2 nd Order Input Intercept (IIP2) VHF, UHF1, UHF2 700, 800 and 900 MHz	41 35	60 50		dBm dBm
RF to IF Isolation ¹ VHF, UHF1, UHF2 700, 800 and 900 MHz	35 25	50 45		dB dB
LO to IF Isolation	20	30		dB
LO to RF Isolation	25	30		dB

Note 1: The RF to IF Isolation is measured with an input frequency equal with IF.



Figure 3. Pin Configuration (Top View)

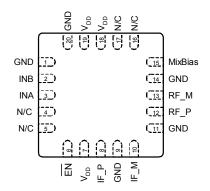


Table 2. Pin Descriptions

Pin #	Symbol	Function
1	GND	Ground
2	INB	Negative LO Input
3	INA	Positive LO Input
4	N/C	No Connect
5	N/C	No Connect
6	EN	Enable Pin (active low)
7	V _{DD}	V_{DD}
8	IF_P	Positive IF port
9	GND	Ground
10	IF_M	Negative IF port
11	GND	Ground
12	RF_P	Positive RF Input
13	RF_M	Negative LO Input
14	GND	Ground
15	MixBias	External Mixer Bias
16	N/C	No Connect
17	N/C	No Connect
18	V _{DD}	V _{DD}
19	V _{DD}	V_{DD}
20	GND	Ground

The RF and IF pins are differential signals connected directly to the passive mixer. The LO input can be differential or single-ended.

Table 3. Operating Ranges

Symbol	Parameters/Conditions	Min	Тур	Max	Units
V _{DD}	V _{DD} Power Supply Voltage	2.9	3.0	3.1	V
T _{OP}	Operating temperature range	-40		85	°C

Moisture Sensitivity Level

The Moisture Sensitivity Level rating for the PE4150 in the 20-lead 4x4 QFN package is MSL1.

Table 4. Absolute Maximum Ratings

Symbol	Parameters/Conditions	Min	Max	Units
V_{DD}	Supply Voltage		4.0	°C
V _{DS}	Maximum DC plus peak AC across drain-source		±3.3	٧
I _{DS-DC}	Maximum DC current across drain-source		6	mA
I _{DS-AC}	Maximum AC current across drain-source		36	mA _{p-p}
T _{ST}	Storage temperature range	-65	150	°C
Tj	Operating Junction Temperature		125	°C
V _{ESD}	ESD Voltage (HBM, MIL_STD 883 Method 3015.7)		1000	٧

Exceeding absolute maximum ratings may cause permanent damage. Operation should be restricted to the limits in the Operating Ranges table. Operation between operating range maximum and absolute maximum for extended periods may reduce reliability.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS™ device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS™ devices are immune to latch-up.

Device Description

The PE4150 passive broadband Quad MOSFET array is designed for use in up-conversion and down-conversion applications for high performance systems such as mobile radios, cellular infrastructure equipment, and STB/CATV systems.

The PE4150 is an ideal mixer core for a wide range of mixer products, including module level solutions that incorporate baluns or other single-ended matching structures enabling three-port operation.

The performance level of this passive mixer is made possible by the very high linearity afforded by Peregrine's UltraCMOS™ process.



Evaluation Kit

The Mixer Evaluation Kit board was designed to ease customer evaluation of the PE4150 Quad MOSFET Mixer with intergrated LO amplifier.

The RF and IF ports are connected through 50ohm transmission lines and 1:4 transmission line transformers to J5 and J7, respectively. The LO ports are connected through 50ohm transmission lines to J4 and J6, respectively, and can support either a single-ended or differential signal drive. With a single-ended input, no termination is needed on the un-used port.

The board is constructed of a two metal layer FR4 with a total thickness of 0.062". The bottom layer provides ground for the RF transmission lines. The transmission lines were designed using a coplanar waveguide with ground plane model using a trace width of 0.037", trace gaps of 0.008", dielectric thickness of 0.059" and metal thickness of 0.0015".

J3 provides an optional external DC bias that can be applied to the LO input, if there is DC component to the applied RF input. To use this option, transformers T2 and T3 must be carefully chosen to allow the use of a non-zero commonmode level.

J9 can be used to enable or disable the part. The chip enable /EN is active low.

De-coupling capacitors are provided on the VDD traces. These capacitors should be placed as close to the DVDD pin as possible.

Applications Support

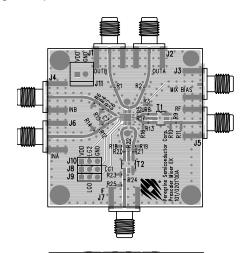
If you have a problem with your evaluation kit or if you have applications questions, please contact applications support:

E-Mail: help@psemi.com (fastest response)

Phone: (858) 731-9400

Figure 4. Evaluation Board Layout

Peregrine Specification 101/0201



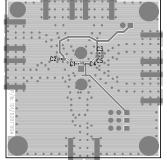
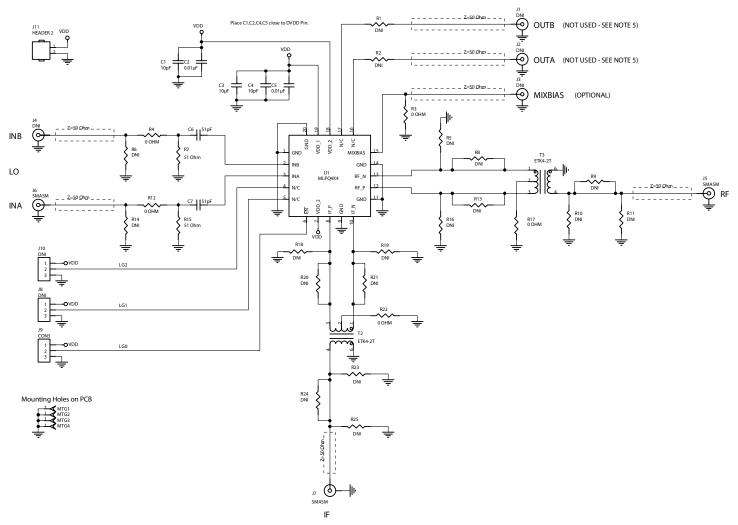




Figure 5. Evaluation Board Schematic

Peregrine Specification 102/0396



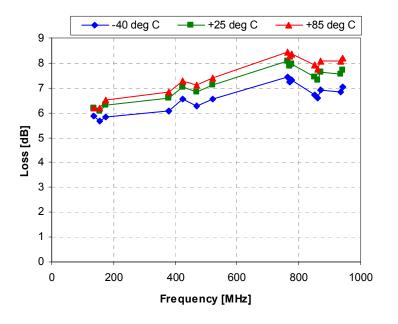
NOTES:

- 1. USE 101-0201-00A PCB.
- CONTAINS PARTS AND ASSEMBLIES SUSCEPTIBLE TO DAMAGE BY ELECTROSTATIC DISCHARGE (ESD)
- 3. LO INPUT CAN BE DIFFERENTIAL OR SINGLE ENDED (INA/INB)
- 4. WITH SINGLE ENDED LO INPUT, NO TERMINATION IS NEEDED ON UNUSED PORT.
- 5. PINS 16 AND 17 ARE INTERNALLY DISCONNECTED.



Typical Performance Plots

Figure 6. Conversion Loss vs Temperature (VDD = 3V; LO Pwr = -10 dBm)



(Temp = 25 deg C)

Figure 7. Conversion Loss vs LO Power & VDD

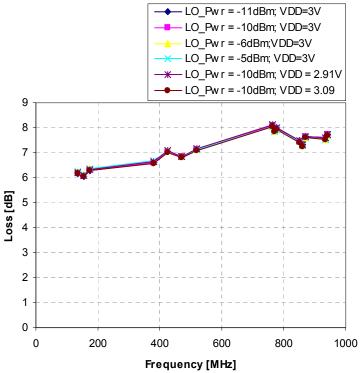


Figure 8. Linearity vs Temperature (VDD = 3V; LO Pwr = -10 dBm)

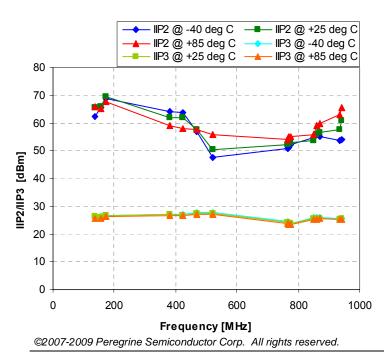
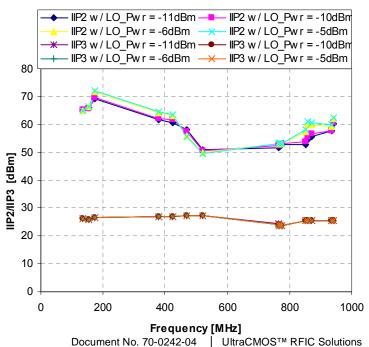


Figure 9. Linearity vs LO Power (VDD = 3V; Temp = +25 deg C)





Typical Performance Plots

Figure 10. Linearity vs VDD

$$(Temp = +25 deg C; LO Pwr = -10 dBm)$$

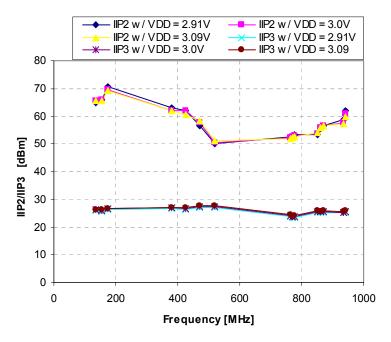


Figure 11. Isolation vs Temperature (VDD = 3V; LO Pwr = -10 dBm)

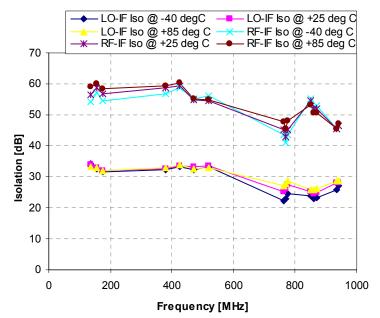


Figure 12. Isolation vs LO Power

$$(VDD = 3V; Temp = +25 deg C)$$

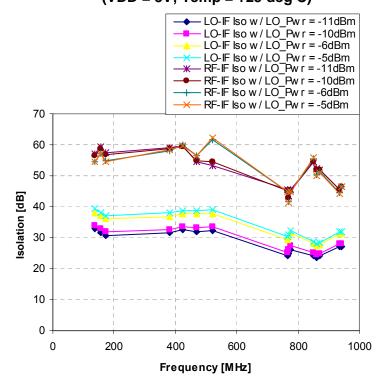


Figure 13. Isolation vs VDD

(Temp = +25 deg C; LO Pwr = -10 dBm)

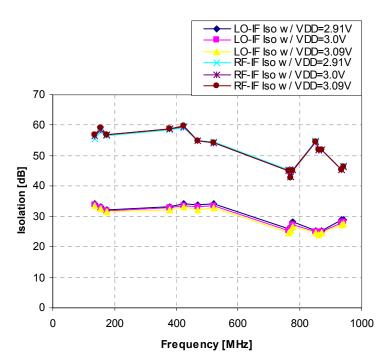
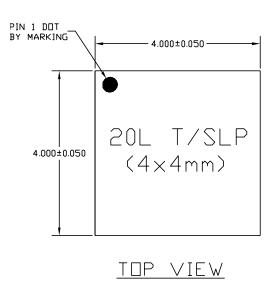
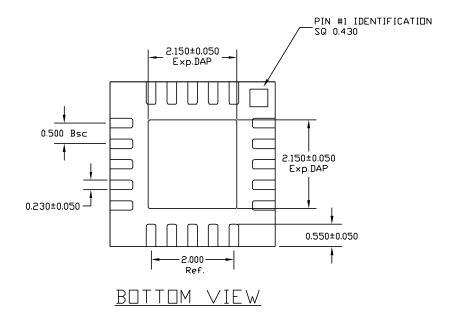




Figure 14. Package Drawing

4x4 mm 20-lead QFN





 $\frac{\text{N}\square \, \text{TE:}}{\text{ID TSLP AND SLP SHARE THE SAME EXPOSE OUTLINE}}$ BUT WITH DIFFERENT THICKNESS:

		TSLP	SLP
	MAX.	0.800	0.900
ΙΑ	N□M.	0.750	0.850
	M]N.	0.700	0.800

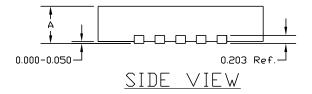
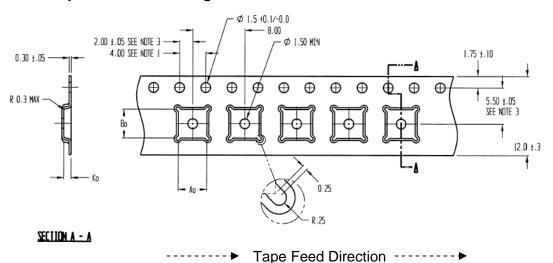




Figure 15. Tape and Reel Drawing



NOTES:

1. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ±0.2

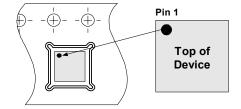
CAMBER IN COMPLIANCE WITH EIA 481

3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE

 $A_0 = 4.35$

 $B_0 = 4.35$

 $K_0 = 1.1$



Device Orientation in Tape

Figure 16. Marking Specification



YYWW = Date Code (Year, Work Week) ZZZZZ = Last five digits of PSC Lot Number

Table 5. Ordering Information

Order Code	Part Marking	Description	Package	Shipping Method
EK-4150-01	PE4150 -EK	PE4150 – 20QFN 4x4mm-EK	Evaluation Kit	1 / Box
PE4150 MLI	4150	PE4150 G - 20QFN 4x4mm-75A	Green 20-lead 4x4mm QFN	75 units / Tube
PE4150 MLI-Z	4150	PE4150 G –20QFN 4x4mm-3000C	Green 20-lead 4x4mm QFN	3000 units / T&R



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For a list of representatives in your area, please refer to our Web site at: www.psemi.com

Data Sheet Identification

Advance Information

The product is in a formative or design stage. The data sheet contains design target specifications for product development. Specifications and features may change in any manner without notice.

Preliminary Specification

The data sheet contains preliminary data. Additional data may be added at a later date. Peregrine reserves the right to change specifications at any time without notice in order to supply the best possible product.

Product Specification

The data sheet contains final data. In the event Peregrine decides to change the specifications, Peregrine will notify customers of the intended changes by issuing a CNF (Customer Notification Form).

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